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Hex Level Shifter for TTL to CMOS or CMOS to CMOS

The MC14504B is a hex non–inverting level shifter using CMOS technology. The level shifter will shift a TTL signal to CMOS logic levels for any CMOS supply voltage between 5 and 15 volts. A control input also allows interface from CMOS to CMOS at one logic level to another logic level: Either up or down level translating is accomplished by selection of power supply levels V_{DD} and V_{CC} . The V_{CC} level sets the input signal levels while V_{DD} selects the output voltage levels.

Features

- UP Translates from a Low to a High Voltage or DOWN Translates from a High to a Low Voltage
- Input Threshold Can Be Shifted for TTL Compatibility
- No Sequencing Required on Power Supplies or Inputs for Power Up or Power Down
- 3 to 18 Vdc Operation for V_{DD} and V_{CC}
- Diode Protected Inputs to V_{SS}
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load Over the Rated Temperature Range
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

| Symbol | Parameter | Value | Unit |
|------------------------------------|---|-------------------------------|------|
| V _{CC} | DC Supply Voltage Range | -0.5 to +18.0 | V |
| V_{DD} | DC Supply Voltage Range | -0.5 to +18.0 | V |
| V _{in} | Input Voltage Range (DC or Transient) | -0.5 to +18.0 | V |
| V _{out} | Output Voltage Range (DC or Transient) | -0.5 to V _{DD} + 0.5 | V |
| I _{in} , I _{out} | Input or Output Current (DC or Transient) per Pin | ±10 | mA |
| P _D | Power Dissipation, per Package (Note 1) | 500 | mW |
| T _A | Ambient Temperature Range | -55 to +125 | °C |
| T _{stg} | Storage Temperature Range | -65 to +150 | °C |
| TL | Lead Temperature (8–Second Soldering) | 260 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: "D/DW" Packages: -7.0 mW/°C From 65°C To 125°C



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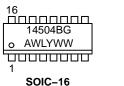
SOIC-16 D SUFFIX CASE 751B

F SUFFIX CASE 966 TSSOP-16 DT SUFFIX CASE 948F

PIN ASSIGNMENT

| | | | _ |
|--------------------|----|----|--------------------|
| V _{CC} | 1● | 16 | V _{DD} |
| A _{out} [| 2 | 15 |] F _{out} |
| A _{in} [| 3 | | F _{in} |
| B _{out} [| 4 | 13 | MODE |
| B _{in} [| 5 | 12 | □ E _{out} |
| Cout [| 6 | 11 | ∃ E _{in} |
| C _{in} [| 7 | 10 | D _{out} |
| V _{SS} [| 8 | 9 | D _{in} |
| | | | |

MARKING DIAGRAMS







TSSOP-16

A = Assembly Location WL, L = Wafer Lot

WL, L = Water Lot
YY, Y = Year
WW, W = Work Week
G or = Pb-Free Indicator

(Note: Microdot may be in either location)

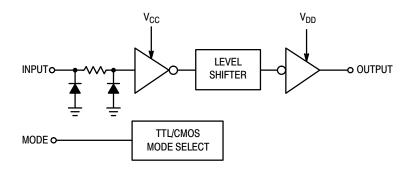
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \le (V_{in} \text{ or } V_{out}) \le V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either VSS or VDD). Unused outputs must be left open.

LOGIC DIAGRAM



| Mode Select | Input Logic Levels | Output Logic Levels |
|----------------------|-----------------------|------------------------|
| 1 (V _{CC}) | TTL | CMOS |
| 0 (V _{SS}) | CMOS | CMOS |

1/6 of package shown.

ORDERING INFORMATION

| Device | Package | Shipping [†] | |
|-----------------|------------------------|--------------------------|--|
| MC14504BDG | SOIC-16 | 48 Units / Rail | |
| NLV14504BDG* | (Pb-Free) | | |
| MC14504BDR2G | SOIC-16 | 2500 Units / Tape & Reel | |
| NLV14504BDR2G* | (Pb-Free) | | |
| MC14504BDTG | TSSOP-16 | 96 Units / Rail | |
| NLV14504BDTG* | (Pb-Free) | | |
| MC14504BDTR2G | TSSOP-16 | 2500 Units / Tape & Reel | |
| NLV14504BDTR2G* | (Pb-Free) | | |
| MC14504BFELG | SOEIAJ-16 (Pb-Free) | 2000 Units / Tape & Reel | |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP

Capable.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

| | | ., | W | - 5 | 5°C | | 25°C | | 125°C | | |
|---|---------------------------------------|--------------------------------|----------------------------|----------------------------------|---------------------------------|----------------------------------|------------------------------------|---------------------------------|----------------------------------|---------------------------------|------|
| Characteristic | Symbol | V _{CC} Vdc | V _{DD} Vdc | Min | Max | Min | Typ (Note 2) | Max | Min | Max | Unit |
| Output Voltage "0" Lev | | - - - | 5.0 10 1 5 | - - - | 0.05 0.05 0.05 | - - - | 0 0 0 | 0.05 0.05 0.05 | - - - | 0.05 0.05 0.05 | Vdc |
| V _{in} = V _{CC} "1" Lev | V _{OH} | - - - | 5.0 10 15 | 4.95 9.95 14.95 | - - - | 4.95 9.95 14.95 | 5.0 10 15 | - - - | 4.95 9.95 14.95 | - - - | Vdc |
| $\label{eq:local_problem} \begin{array}{lll} \text{Input Voltage} & \text{``0'' Lev} \\ \text{($V_{\text{OL}} = 1.0 \text{ Vdc)}$ TTL-CMOS} \\ \text{($V_{\text{OL}} = 1.5 \text{ Vdc)}$ CMOS-CMOS} \\ \text{($V_{\text{OL}} = 1.0 \text{ Vdc)}$ CMOS-CMOS} \\ \text{($V_{\text{OL}} = 1.5 \text{ Vdc)}$ CMOS-CMOS} \\ \text{($V_{\text{OL}} = 1.5 \text{ Vdc)}$ CMOS-CMOS} \\ \end{array}$ | el V _{IL} | 5.0 5.0 5.0 5.0 10 | 10 15 10 15 15 | - - - - | 0.8 0.8 1.5 1.5 3.0 | - - - - | 1.3 1.3 2.25 2.25 4.5 | 0.8 0.8 1.5 1.5 3.0 | - - - - | 0.8 0.8 1.4 1.5 2.9 | Vdc |
| Input Voltage "1" Lev $(V_{OH} = 9.0 \text{ Vdc})$ TTL-CMOS $(V_{OH} = 13.5 \text{ Vdc})$ TTL-CMOS $(V_{OH} = 9.0 \text{ Vdc})$ CMOS-CMOS $(V_{OH} = 13.5 \text{ Vdc})$ CMOS-CMOS $(V_{OH} = 13.5 \text{ Vdc})$ CMOS-CMOS | el V _{IH} | 5.0 5.0 5.0 5.0 10 | 10 15 10 15 15 | 2.0 2.0 3.6 3.6 7.1 | - - - - | 2.0 2.0 3.5 3.5 7.0 | 1.5 1.5 2.75 2.75 5.5 | - - - - | 2.0 2.0 3.5 3.5 7.0 | | Vdc |
| Output Drive Current $ (V_{OH} = 2.5 \text{ Vdc}) $ Source $ (V_{OH} = 4.6 \text{ Vdc}) $ $ (V_{OH} = 9.5 \text{ Vdc}) $ $ (V_{OH} = 13.5 \text{ Vdc}) $ | e I _{OH} | - - - | 5.0 5.0 10 15 | - 3.0 -0.64 - 1.6 - 4.2 | - - - - | - 2.4 -0.51 - 1.3 - 3.4 | - 4.2 - 0.88 - 2.25 - 8.8 | - - - - | - 1.7 -0.36 - 0.9 - 2.4 | - - - | mAdc |
| $(V_{OL} = 0.4 \text{ Vdc})$ Sir $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$ | k I _{OL} | - - - | 5.0 10 15 | 0.64 1.6 4.2 | - - - | 0.51 1.3 3.4 | 0.88 2.25 8.8 | - - - | 0.36 0.9 2.4 | 1 1 1 | mAdc |
| Input Current | l _{in} | - | 15 | - | ±0.1 | - | ±0.00001 | ±0.1 | - | ±1.0 | μAdc |
| Input Capacitance (V _{in} = 0) | C _{in} | _ | _ | - | _ | _ | 5.0 | 7.5 | - | - | pF |
| Quiescent Current (Per Package) CMOS–CMOS Mode | I _{DD} or I _{CC} | - - - | 5.0 10 15 | - - - | 0.05 0.10 0.20 | - - - | 0.0005 0.0010 0.0015 | 0.05 0.10 0.20 | - - - | 1.5 3.0 6.0 | μAdc |
| Quiescent Current (Per Package) TTL-CMOS Mode | I _{DD} | 5.0 5.0 5.0 | 5.0 10 15 | - - - | 0.5 1.0 2.0 | - - - | 0.0005 0.0010 0.0015 | 0.5 1.0 2.0 | - - - | 3.8 7.5 15 | μAdc |
| Quiescent Current (Per Package) TTL-CMOS Mode | I _{CC} | 5.0 5.0 5.0 | 5.0 10 15 | - - - | 5.0 5.0 5.0 | - - - | 2.5 2.5 2.5 | 5.0 5.0 5.0 | - - - | 6.0 6.0 6.0 | mAdc |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

SWITCHING CHARACTERISTICS ($C_L = 50 \ pF, \ T_A = 25^{\circ}C$)

| | | | V | v | | Limits | | |
|--------------------------------|-------------------------------------|-------------------|-----|------------------------|-----|-----------------|-----|------|
| Characteristic | Symbol Shifting Mode | | | V _{DD} Vdc | Min | Typ (Note 3) | Max | Unit |
| Propagation Delay, High to Low | t _{PHL} | TTL - CMOS | 5.0 | 10 | _ | 140 | 280 | ns |
| | | $V_{DD} > V_{CC}$ | 5.0 | 15 | _ | 140 | 280 | |
| | | CMOS - CMOS | 5.0 | 10 | _ | 120 | 240 | |
| | | $V_{DD} > V_{CC}$ | 5.0 | 15 | _ | 120 | 240 | |
| | | | 10 | 15 | _ | 70 | 140 | |
| | | CMOS - CMOS | 10 | 5.0 | _ | 185 | 370 | |
| | | $V_{CC} > V_{DD}$ | 15 | 5.0 | _ | 185 | 370 | |
| | | | 15 | 10 | _ | 175 | 350 | |
| Propagation Delay, Low to High | t _{PLH} | TTL - CMOS | 5.0 | 10 | _ | 170 | 340 | ns |
| | | $V_{DD} > V_{CC}$ | 5.0 | 15 | _ | 160 | 320 | |
| | | CMOS - CMOS | 5.0 | 10 | _ | 170 | 340 | |
| | | $V_{DD} > V_{CC}$ | 5.0 | 15 | _ | 170 | 340 | |
| | | | 10 | 15 | _ | 100 | 200 | |
| | | CMOS - CMOS | 10 | 5.0 | _ | 275 | 550 | |
| | | $V_{CC} > V_{DD}$ | 15 | 5.0 | _ | 275 | 550 | |
| | | | 15 | 10 | _ | 145 | 290 | |
| Output Rise and Fall Time | t _{TLH} , t _{THL} | ALL | - | 5.0 | - | 100 | 200 | ns |
| | | | _ | 10 | _ | 50 | 100 | |
| | | | _ | 15 | _ | 40 | 80 | |

^{3.} Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

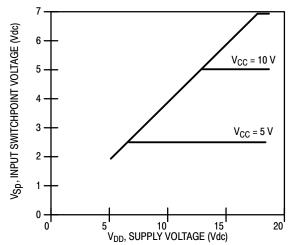
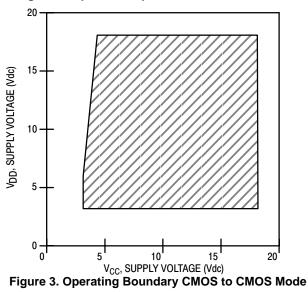


Figure 1. Input Switchpoint CMOS to CMOS Mode



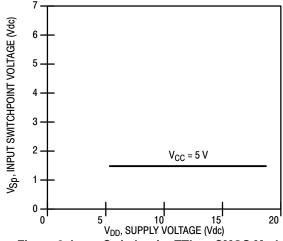


Figure 2. Input Switchpoint TTL to CMOS Mode

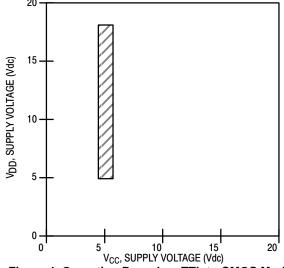
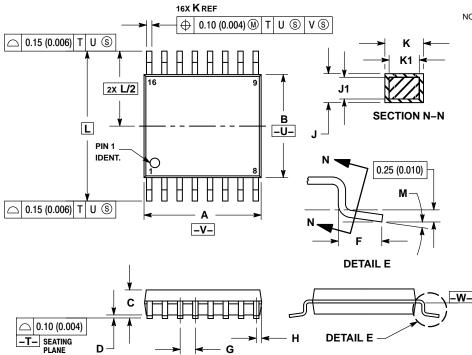


Figure 4. Operating Boundary TTL to CMOS Mode

PACKAGE DIMENSIONS

TSSOP-16 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948F **ISSUE B**



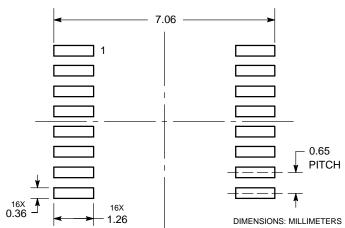
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
 - ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS.
 - FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

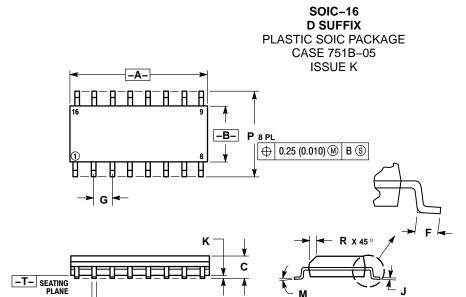
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K
 - (0.003) TOTAL IN EXCESS OF THE K
 DIMENSION AT MAXIMUM MATERIAL
 - CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| | MILLIN | IETERS | INC | HES |
|-----|--------|--------|-------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 4.90 | 5.10 | 0.193 | 0.200 |
| В | 4.30 | 4.50 | 0.169 | 0.177 |
| С | | 1.20 | | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 | BSC | 0.026 | BSC |
| Н | 0.18 | 0.28 | 0.007 | 0.011 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 | BSC | 0.252 | BSC |
| М | 0° | 8° | 0° | 8° |

SOLDERING FOOTPRINT



PACKAGE DIMENSIONS



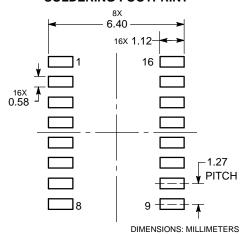
D 16 PL

⊕ 0.25 (0.010) M T B S A S

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

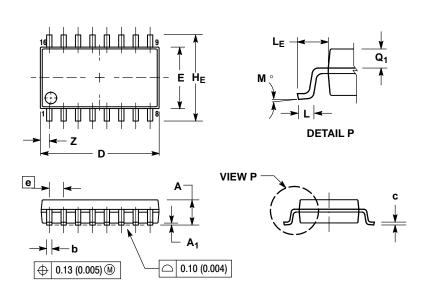
| | MILLIN | IETERS | INC | HES |
|-----|--------|--------|-------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 9.80 | 10.00 | 0.386 | 0.393 |
| В | 3.80 | 4.00 | 0.150 | 0.157 |
| c | 1.35 | 1.75 | 0.054 | 0.068 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.40 | 1.25 | 0.016 | 0.049 |
| G | 1.27 | BSC | 0.050 | BSC |
| 7 | 0.19 | 0.25 | 0.008 | 0.009 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| M | 0° | 7° | 0° | 7° |
| Р | 5.80 | 6.20 | 0.229 | 0.244 |
| R | 0.25 | 0.50 | 0.010 | 0.019 |

SOLDERING FOOTPRINT



PACKAGE DIMENSIONS

SOEIAJ-16 **F SUFFIX** PLASTIC EIAJ SOIC PACKAGE **CASE 966 ISSUE A**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI DIMENSION Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
- I. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE, MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

| | MILLIN | IETERS | INC | HES | |
|----------------|--------|--------|-----------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | | 2.05 | | 0.081 | |
| A ₁ | 0.05 | 0.20 | 0.002 | 0.008 | |
| b | 0.35 | 0.50 | 0.014 | 0.020 | |
| С | 0.10 | 0.20 | 0.007 | 0.011 | |
| D | 9.90 | 10.50 | 0.390 | 0.413 | |
| E | 5.10 | 5.45 | 0.201 | 0.215 | |
| е | 1.27 | BSC | 0.050 BSC | | |
| HE | 7.40 | 8.20 | 0.291 | 0.323 | |
| Г | 0.50 | 0.85 | 0.020 | 0.033 | |
| F | 1.10 | 1.50 | 0.043 | 0.059 | |
| M | 0 ° | 10 ° | 0 ° | 10 ° | |
| Q_1 | 0.70 | 0.90 | 0.028 | 0.035 | |
| Z | | 0.78 | | 0.031 | |

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